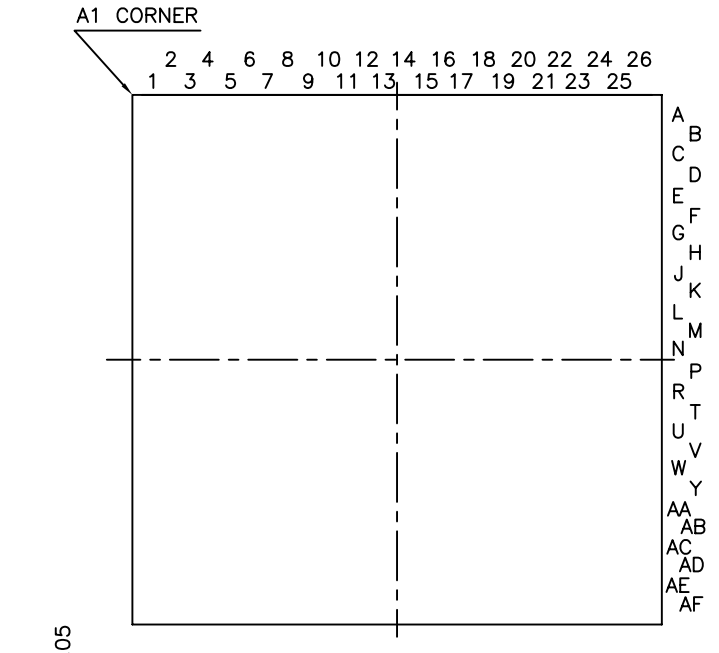
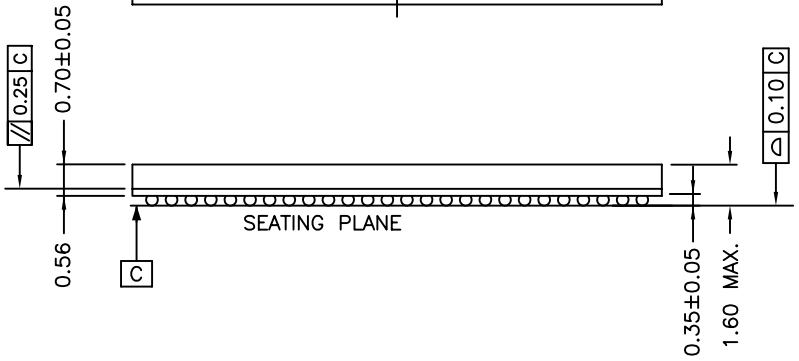
REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	–	**	101259	NEW RELEASE	05/25/00	N/A
1	–	*A	106857	CHG. DIM. ON BALL HEIGHT & FLATNESS TOL.	05/01/01	N/A
1	–	*B	113920	CHG. DIM. ON BALL HEIGHT/ADD SUBSTRATE DIM./ADD MOLD CAP DIM.	03/13/02	N/A
1	–	*C	2813799	Changed Template and Title from 676 FBGA PKG. OUTL. (27x27x1.6MM) to PACKAGE OUTLINE, 676L FBGA 27X27X1.6MM BB676.	11/27/09	QAD
1	–	*D	3352034	UPDATE SPECS FOR SUNSET REVIEW. NO CHANGE.	08/23/11	QAD
1	–	*E	3726092	Sunset Review, Added Package Weight – Refer to PMDD spec.	08/28/12	QAD

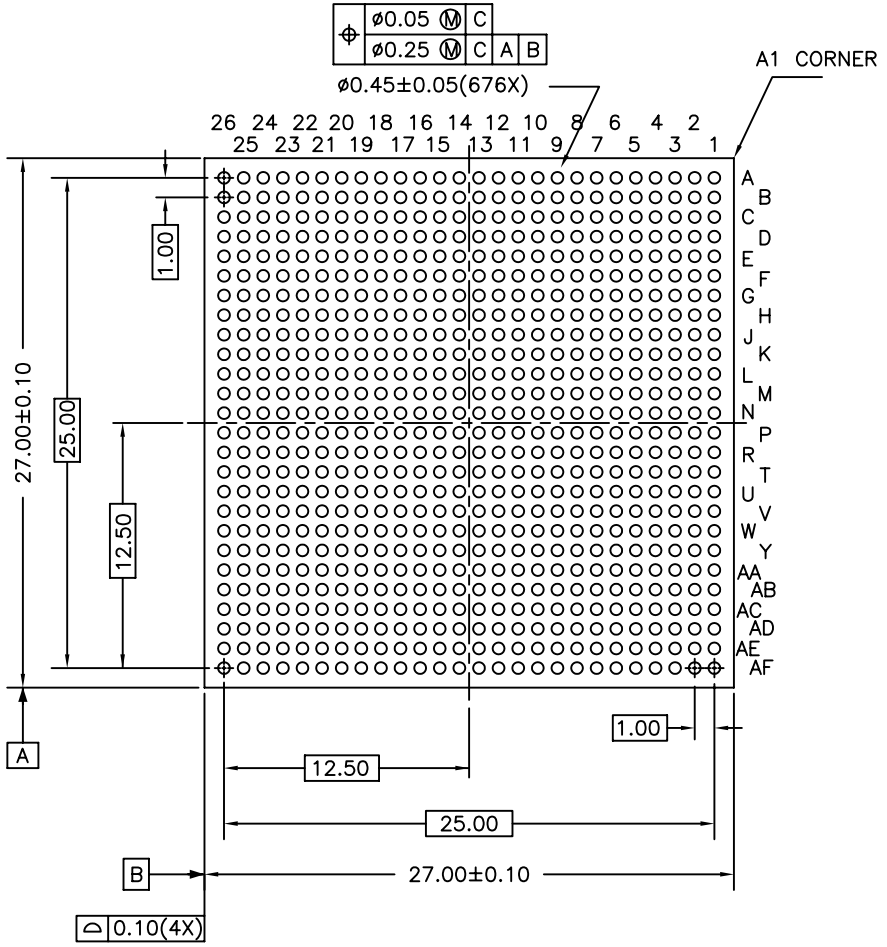
TOP VIEW





Package Weight – Refer to PMDD spec.

BOTTOM VIEW



UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON: DECIMALS .XX ± 0.05, .XXX ±, .XXXX + ANGLES ± 1°	DESIGNED BY HTN	DATE 03/13/02	CYPRESS Company Confidential
	DRAWN BY ROWI	DATE 08/28/12	TITLE: PACKAGE OUTLINE, 676L FBGA 27X27X1.6MM BB676
	CHECKED BY QAD	DATE 08/28/12	
	APPROVED BY EDCA	DATE 08/28/12	
MATERIAL N/A	APPROVED BY QAD	DATE 08/28/12	SIZE A / PART NO. BB676 / DWG NO 51-85125 / REV *E
FINISH N/A	APPROVED BY PRC	DATE 08/28/12	SCALED TO FIT / N/A / SHEET 1 OF 1

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